

FIG. 1

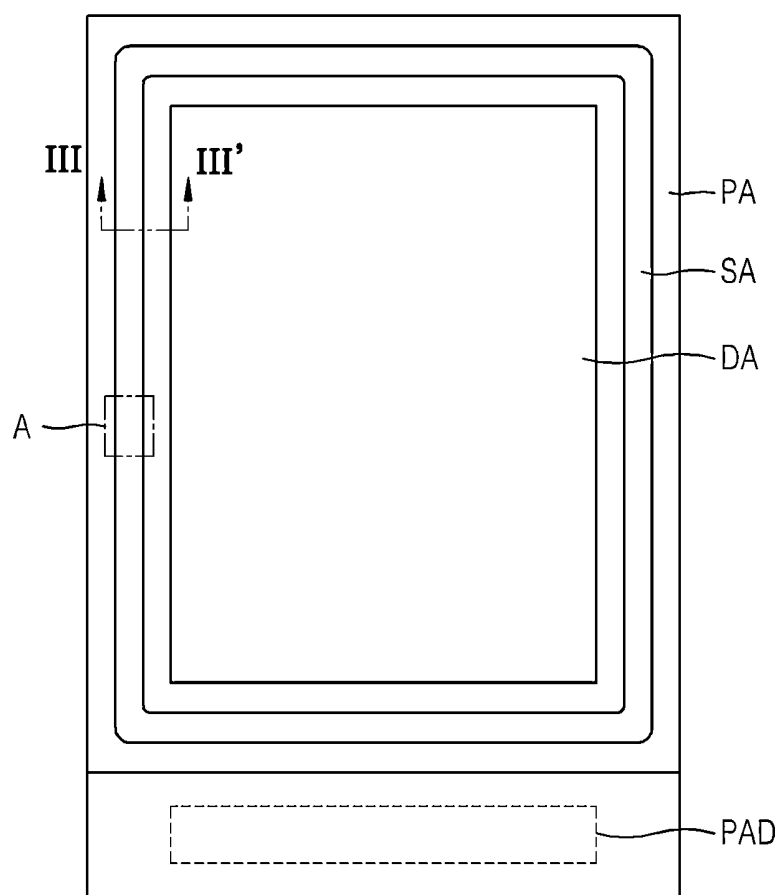
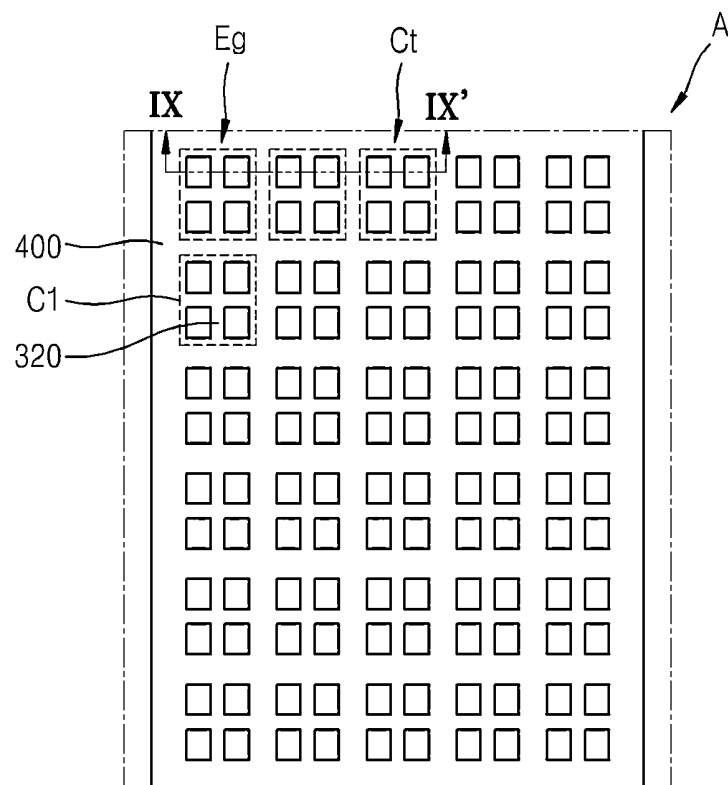


FIG. 2



The diagram illustrates a cross-sectional view of a semiconductor device, divided into two main sections: SA (Source Area) and DA (Drain Area). In the SA section, a substrate 10 is covered by a gate stack 17, which includes layers 11, 13, 15, and 19. A source contact 316 is formed on top of the gate stack. The DA section features a similar gate stack 17 and a drain contact 316. Above the DA region, an OLED layer is depicted, consisting of layers 121, 122, and 123. Various other components are labeled, including 10, 11, 13, 15, 17, 19, 20, 218a, 218b, 216, 212, sTFT, dTFT, 112, 112a, 112c, 112b, 212a, 212c, 212b, 314, C1, 400, 15a, 15b, 15c, 316a, 316b, 17b, 17a, 118a, 114, 118b, 121, 122, 123, and 30.

FIG. 5

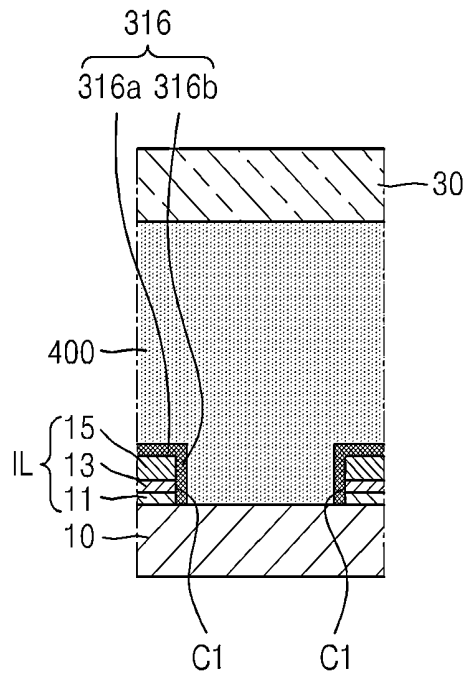


FIG. 6

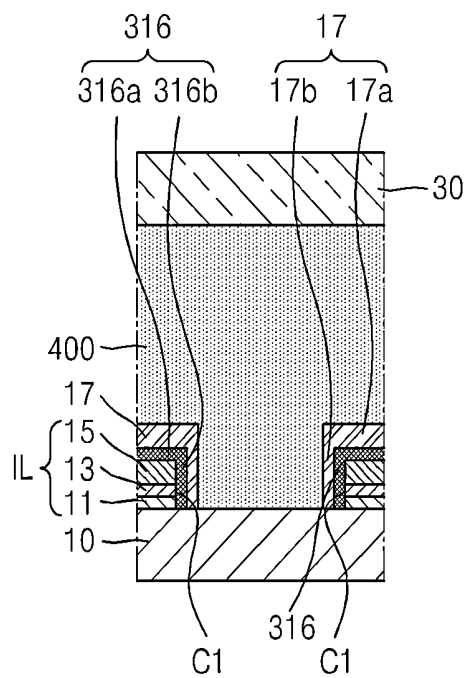
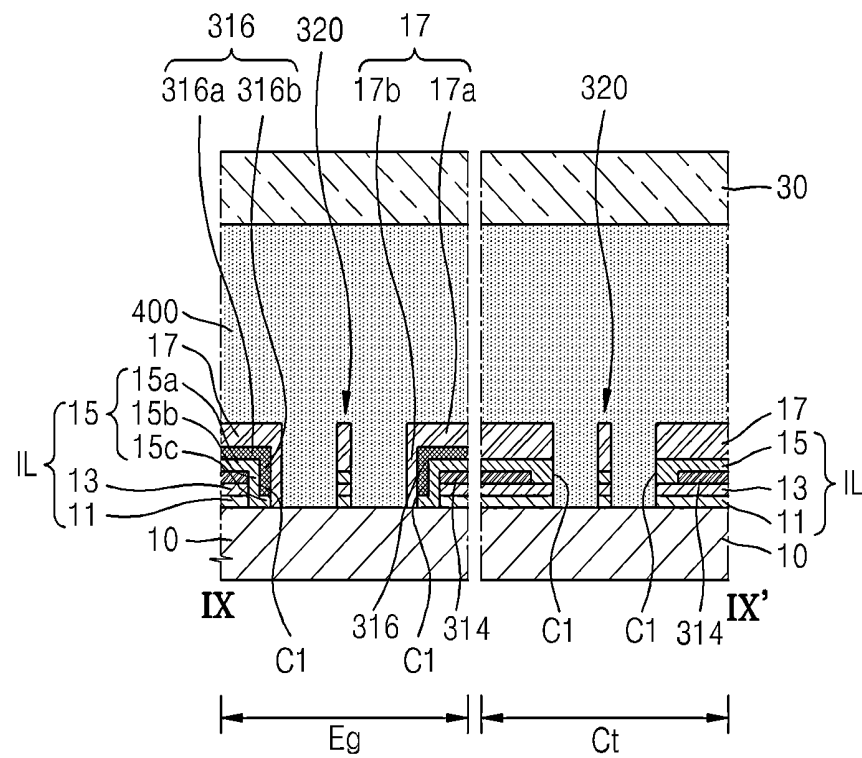


FIG. 9



ORGANIC LIGHT-EMITTING DISPLAY APPARATUS

RELATED APPLICATION

This application claims the benefit of Korean Patent Application No. 10-2013-0126114, filed on Oct. 22, 2013, in the Korean Intellectual Property Office, the disclosure of which is incorporated herein by reference in its entirety.

BACKGROUND

1. Field

The present disclosure relates to an organic light-emitting display apparatus.

2. Description of the Related Art

An organic light-emitting display apparatus includes a hole injection electrode, an electron injection electrode, and an organic light-emitting device including an organic emission layer formed between the hole injection electrode and the electron injection electrode. The organic light-emitting display apparatus is a self-emission display apparatus where holes injected from the hole injection electrode, and electrons injected from the electron injection electrode are combined in the organic emission layer to form excitons, and light is emitted while the excitons drop from an excited state to a ground state.

The organic light-emitting display apparatus, which is the self-emission display apparatus, does not require separate light sources, and thus may be operated at a low voltage, and formed as a thin and lightweight structure. Also, the organic light-emitting display apparatus has high-quality features such as wide viewing angles, excellent contrast, and quick response, and thus has a wide range of applications from personal portable devices such as MP3 players and cell phones to televisions.

SUMMARY

One or more embodiments of the present invention include an organic light-emitting display apparatus.

Additional aspects will be set forth in part in the description that follows and, in part, will be apparent from the description, or may be learned by practice of the presented embodiments.

According to one or more embodiments of the present invention, there is an organic light-emitting display apparatus including: a lower substrate including a major surface, which comprises a display area for displaying an image thereon and a sealing area surrounding the display area when viewed in a direction perpendicular to the major surface; an insulating structure disposed over the lower substrate in both the display area and the sealing area; a plurality of openings formed through the insulating structure in the sealing area to expose the lower substrate therethrough, the openings comprising inner side surfaces; a first conductive layer including a first portion over the insulating structure extending in a horizontal direction that is generally parallel to the major surface, and a second portion extending on at least part of the inner side surfaces of the openings in a vertical direction that is generally perpendicular to the major surface; an upper substrate placed over the lower substrate; and a sealing member interposed between the lower substrate and the upper substrate in the sealing area thereof and filling the openings, thereby integrating the lower and upper substrates.

The insulating structure may include a plurality of insulating layers.

The plurality of insulating layers may comprise a first insulating layer and a second insulating layer over the first insulating layer. The apparatus may further comprise a second conductive layer interposed between the first and second insulating layers of the insulating structure.

The second insulating layer may include: a first portion formed over the second conductive layer and extending generally in the horizontal direction; and a second portion formed on the side surface of the second conductive layer and extending generally in the vertical direction, thereby providing at least part of the side surface of the openings.

The second insulating layer may further include a third portion extending from second portion generally in the horizontal direction.

The apparatus may further include a third insulating layer disposed on the first conductive layer.

The third insulating layer may include: a first portion extending generally in the horizontal direction on the first portion of the first conductive layer; and a second portion formed on the second portion of the first conductive layer and extending generally in the vertical direction.

The apparatus may further include a partition disposed inside the openings.

The partition may include generally the same layered structure as the insulating structure.

The apparatus may further comprise a first thin film transistor (TFT) including a first activation layer and a first gate electrode disposed in the display area; and a second TFT including a second activation layer and a second gate electrode disposed in the display area. The first and second gate electrodes may be disposed at different levels.

The first conductive layer may be arranged at the same level as the second gate electrode, and the second conductive layer may be arranged at the same level as the first gate electrode.

The apparatus may further comprise a first gate insulating layer interposed between the first activation layer and the first gate electrode, and a second gate insulating layer disposed on the first gate electrode. The second activation layer may be disposed at the same level as the first activation layer, and the second gate electrode may be disposed on the second gate insulating layer over the second activation layer.

The first insulating layer in the sealing area may include a portion that extends from the first gate insulating layer in the display area, and the second insulating layer may include a portion that extends from the second gate insulating layer in the display area.

The apparatus may further comprise a driving thin film transistor comprising a driving activation layer and a driving gate electrode; a capacitor including the driving gate electrode functioning as a lower electrode, and an upper electrode; a first gate insulating layer interposed between the driving activation layer and the driving gate electrode; and a second gate insulating layer interposed between the driving gate electrode and the upper electrode.

The first conductive layer may be disposed at the same level as the upper electrode, and the second conductive layer may be disposed at the same level as the driving gate electrode.

The first insulating layer in the sealing area may include a portion that extends from the first gate insulating layer in the display area, and the second insulating layer in the sealing area may include a portion that extends from the second gate insulating layer in the display area.

The first conductive layer may be disposed only at an edge of the sealing area.

The insulating layer, the first conductive layer, and the second conductive layer may be disposed at an edge of the sealing area, and the insulating layer and the second conductive layer may be disposed at a center of the sealing area.

The apparatus may further include at least one organic light-emitting device disposed in the display area. The at least one organic light-emitting device may include: a pixel electrode; an opposite electrode placed over the pixel electrode; and an intermediate layer arranged between the pixel electrode and the opposite electrode, and including an organic emission layer.

The sealing member may include frit, and may directly contact exposed portions of the lower substrate through the openings.

BRIEF DESCRIPTION OF THE DRAWINGS

These and/or other aspects will become apparent and more readily appreciated from the following description of the embodiments, taken in conjunction with the accompanying drawings in which:

FIG. 1 is a schematic plan view of an organic light-emitting display apparatus, according to an embodiment of the present invention;

FIG. 2 is a plan view illustrating an enlarged section A of the organic-light-emitting display apparatus, according to an embodiment of the present invention;

FIG. 3 is a cross-sectional view, taken along a line III-III' of FIG. 1, according to an embodiment of the present invention;

FIG. 4 is a schematic cross-sectional view of an organic-light-emitting display apparatus, according to another embodiment of the present invention;

FIG. 5 is a cross-sectional view of a sealing area included in the organic-light-emitting display apparatus, according to another embodiment of the present invention;

FIG. 6 is a cross-sectional view of a sealing area included in the organic light-emitting display apparatus, according to another embodiment of the present invention;

FIG. 7 is a cross-sectional view of a sealing area included in the organic light-emitting display apparatus, according to another embodiment of the present invention;

FIG. 8 is a cross-sectional view of a sealing area included in the organic light-emitting display apparatus, according to another embodiment of the present invention; and

FIG. 9 is a cross-sectional view, taken along a line IX-IX' of FIG. 2, according to an embodiment of the present invention.

DETAILED DESCRIPTION

Reference will now be made in detail to embodiments, examples of which are illustrated in the accompanying drawings, wherein like reference numerals refer to the like elements throughout. In this regard, the present embodiments may have different forms and should not be construed as being limited to the descriptions set forth herein. Accordingly, the embodiments are merely described below, by referring to the figures, to explain aspects of the present description. As used herein, the term “and/or” includes any and all combinations of one or more of the associated listed items. Expressions such as “at least one of,” when preceding a list of elements, modify the entire list of elements and do not modify the individual elements of the list.

Hereinafter, example embodiments of the invention will be described with reference to the attached drawings. Like reference numerals in the drawings denote like elements, and thus their description will not be repeated.

It will be understood that although the terms “first” and “second” are used herein to describe various elements, these elements should not be limited by these terms. These terms are only used to distinguish one element from another element. Thus, a first element discussed below could be termed a second element, and similarly, a second element may be termed a first element without departing from the teachings of this disclosure.

As used herein, the singular forms “a”, “an” and “the” are intended to include the plural forms as well, unless the context clearly indicates otherwise. It will be further understood that the terms “comprises” and/or “comprising,” when used in this specification, specify the presence of stated features, integers, steps, operations, elements, and/or components, but do not preclude the presence or addition of one or more other features, integers, steps, operations, elements, components, and/or groups thereof.

It will be understood that when an element or layer is referred to as being “on” another element or layer, the element or layer can be directly on another element or layer or intervening elements or layers.

In the drawings, the sizes and the thicknesses of layers and regions are exaggerated for convenience of explanation, and thus the sizes and the thicknesses are not limited thereto.

FIG. 1 is a schematic plan view of an organic light-emitting display apparatus, according to an embodiment of the present invention, FIG. 2 is a plan view illustrating an enlarged section A of FIG. 1, and FIG. 3 is a cross-sectional view, taken along the line III-III' of FIG. 1.

Referring to FIGS. 1 through 3, the organic light-emitting display apparatus includes: a lower substrate 10 including a display area DA including a plurality of pixels and configured to display an image thereon, and a non-display area PA surrounding the display area DA; an upper substrate 30 placed over the lower substrate 10; and a sealing member 400 arranged in the non-display area PA and attaching the lower and upper substrates 10 and 30. An area on which the sealing member 400 is arranged is a sealing area SA.

A pad unit PAD may be arranged at an edge of the lower substrate 10 that is not covered with the upper substrate 30.

Although not illustrated in the drawings, the non-display area PA may further include a driving circuit unit for driving the pixels included in the display area DA, and wiring, which may be extended to the pad unit PAD. A flexible printed circuit board (FPCB) may be attached to the pad unit PAD.

The lower substrate 10 may include various materials such as glass, metals, or plastic. The pixels are arranged on the lower substrate 10 in the display area PA, and respective pixels may include thin film transistors (TFTs) (for example, dTFT and sTFT), a capacitor Cst, and an organic light-emitting device (OLED).

In FIG. 3, only a driving thin film transistor (dTFT) and a switching thin film transistor (sTFT) are illustrated. However, each pixel may further include other TFTs performing various functions. Although not illustrated in the drawings, the dTFT may be electrically connected to a pixel electrode 121 included in the OLED via other TFTs.

Referring to FIG. 3, a buffer layer 11 is arranged on the lower substrate 10, and on the buffer layer 11, a driving activation layer 212 of the dTFT, and a switching activation layer 112 of the sTFT are arranged. The buffer layer 11 may be formed of silicon oxide or silicon nitride in order to ensure a surface of the lower substrate 10 is flat, and/or to prevent impurities from penetrating into the activation layers 112 and 212. The activation layers 112 and 212 may include various materials. For example, the activation layers 112 and 212 may contain inorganic semiconductor materials such as amor-

phous silicon or crystalline silicon, and may include source areas **112a** and **212a**, drain areas **112b** and **212b** doped with ion impurities, and channel areas **112c** and **212c** connecting the source areas **112a** and **212a** and the drain areas **112b** and **212b**. As another example, the activation layers **112** and **212** may include an oxide semiconductor or organic semiconductor materials.

A first gate insulating layer **13** formed of silicon oxide and/or silicon nitride is arranged on the buffer layer **11** so as to cover the activation layers **112** and **212**. A switching gate electrode **114** is arranged on the first gate insulating layer **13** over the switching activation layer **112**, and a driving gate electrode **214** may be arranged over the driving activation layer **212**.

The dTFT and the capacitor Cst of the organic light-emitting display apparatus may overlap with each other, and the driving gate electrode **214** may function as a lower electrode of the capacitor Cst.

The switching gate electrode **114** and the driving gate electrode **214** may be formed as a single layer or multiple layers including at least one metal selected from the group consisting of aluminum (Al), platinum (Pt), palladium (Pd), silver (Ag), magnesium (Mg), gold (Au), nickel (Ni), neodymium (Nd), iridium (Ir), calcium (Ca), molybdenum (Mo), titanium (Ti), tungsten (W), and copper (Cu).

On the first gate insulating layer **13**, a second gate insulating layer **15** may be arranged to cover the gate electrodes **114** and **214**, and on the second gate insulating layer **15**, an upper electrode **516** placed over the driving gate electrode **214** functioning as the lower electrode of the capacitor Cst may be arranged.

The upper electrode **516** may be formed as a single layer or multiple layers including at least one selected from the group consisting of Al, Pt, Pd, Ag, Mg, Au, Ni, Nd, Ir, Cr, Li, Ca, Mo, Ti, W, and Cu.

In the organic light-emitting display apparatus described in the present embodiment, since the dTFT and the capacitor Cst are arranged to overlap with each other, an area for the capacitor Cst can be secured such that the capacitor Cst may have enough capacitance in high resolution.

An interlayer insulating layer **17** that is formed as a single layer or multiple layers including materials such as silicon oxide or silicon nitride may be arranged on the second gate insulating layer **15** in order to cover the upper electrode **516**. On the interlayer insulating layer **17**, a switching source electrode **118a** and a switching drain electrode **118b** of the sTFT may be arranged. The switching source electrode **118a** and a switching drain electrode **118b** may be electrically connected to the source and drain areas **112a** and **112b** of the switching activation layer **112**, respectively.

The switching source electrode **118a** and the switching drain electrode **118b** may be formed as a single layer or multiple layers including at least one selected from the group consisting of Al, Pt, Pd, Ag, Mg, Au, Ni, Nd, Ir, Cr, Li, Ca, Mo, Ti, W, and Cu.

On the interlayer insulating layer **17**, a planarization layer **19** formed as a single layer or multiple layers including acrylic-based organic materials or benzocyclobutene (BCB) may be arranged in order to cover the switching source electrode **118a** and the switching drain electrode **118b**.

On the planarization layer **19**, the OLED including the pixel electrode **121**, an opposite electrode **123** placed over the pixel electrode **121**, and an intermediate layer **122** arranged therebetween and including an organic emission layer may be arranged.

The pixel electrode **121** is formed of a translucent or transparent electrode or a reflective electrode. When the pixel

electrode **121** is formed of the translucent or transparent electrode, the pixel electrode **121** may be formed of at least one material selected from the group consisting of indium tin oxide (ITO), indium zinc oxide (IZO), zinc oxide (ZnO), indium oxide (In₂O₃), indium gallium oxide (IGO), and aluminum zinc oxide (AZO). When the pixel electrode **121** is formed of the reflective electrode, the pixel electrode **121** may include a reflective layer including at least one selected from the group consisting of Al, Pt, Pd, Ag, Mg, Au, Ni, Nd, Ir, Cr, Li, Ca, Mo, Ti, W, Cu, and compounds thereof, and layers formed of ITO, IZO, ZnO, In₂O₃, IGO, and AZO. However, the present embodiment is not limited thereto, and the pixel electrode **121** may be formed of various materials.

A pixel defining layer **20** may be arranged on the planarization layer **19**. The pixel defining layer **20** includes an opening exposing a center of the pixel electrode **121**, and defines the pixels. Also, the pixel defining layer **20** increases the distance between an end of the pixel electrode **121** and the opposite electrode **123** disposed on the pixel electrode **121**, thereby preventing the generation of an arc, and etc. at the end of the pixel electrode **121**. The pixel defining layer **20** may be formed of organic materials such as polyimide.

The intermediate layer **122** may be arranged on the pixel electrode **121**. As discussed above, the intermediate layer **122** may include the organic emission layer, and may further include at least one of a hole injection layer, a hole transport layer, an electron transport layer, and an electron injection layer. However, one or more embodiments discussed herein are not limited to such examples, and the intermediate layer **122** may include the organic emission layer and various other functional layers.

When the OLED is a full-color OLED, the organic emission layer may be patterned as red, green, and blue emission layers according to red, green, and blue sub-pixels.

The organic emission layer may have a multi-layer structure in which the red, green, and blue emission layers are stacked in order to emit white light, or have a single-layer structure including red, green, and blue emission materials. The OLED including the organic emission layer may emit full-color light by additionally including red, green, and blue color filters.

The opposite electrode **123** is arranged on the intermediate layer **122**. The opposite electrode **123** may be formed of the translucent or transparent electrode or the reflective electrode. When the opposite electrode **123** is formed of the translucent or transparent electrode, the opposite electrode **123** may include at least one selected from the group consisting of Ag, Al, Mg, Li, Ca, Cu, lithium fluoride/calcium (LiF/Ca), LiF/Al, MgAg, and CaAg, and may be formed as a thin film having a thickness of several nanometers to tens of nanometers in order for the light to penetrate the opposite electrode **123**. When the opposite electrode **123** is formed of the reflective electrode, the opposite electrode **123** may include the reflective layer including at least one material selected from the group consisting of Ag, Al, Mg, Li, Ca, Cu, LiF/Ca, LiF/Al, MgAg, and CaAg.

The upper substrate **30** placed over the lower substrate **10** may be formed of various materials such as glass, metals, or plastic. The lower and upper substrates **10** and **30** may be attached by the sealing member **400**. The sealing member **400** may include frit or epoxy, but is not limited thereto.

Referring to FIGS. 2 and 3, on the lower substrate **10** corresponding to the sealing area SA in which the sealing member **400** is arranged, the insulating layer IL including the openings C1, and the first conductive layer **316** including a first area **316a** (e.g., the portion that is parallel to the plane of the lower substrate **10** in FIG. 3) arranged on top surface of

the insulating layer IL, and a second area **316b** (e.g., the portion that is perpendicular to the plane of the lower substrate **10** in FIG. 3) extended along a side portion of the insulating layer IL in an inward direction of the openings **C1** may be arranged.

The insulating layer IL may include the first insulating layers **11** and **13** and the second insulating layer **15**, and between the first insulating layers **11** and **13** and the second insulating layer **15**, the second conductive layer **314** may be arranged. In addition, the first insulating layers **11** and **13** and the second conductive layer **314** may include the same etched surface. That is, the first insulating layers **11** and **13**, and the second conductive layer **314** may be etched using the same mask in a manufacturing procedure.

In the present embodiment, the first and second conductive layers **316** and **314** may be arranged on the same layer (or at the same level) as the upper electrode **516** of the capacitor **Cst**, and the driving gate electrode **214**, and may include the same material, respectively.

The first insulating layers **11** and **13** may be portions that extend from the buffer layer **11** and the first gate insulating layer **13** in the display area DA, and the second insulating layer **15** may be a portion that extends from the second gate insulating layer **15** in the display area DA.

The second insulating layer **15** may include a first area **15a** (e.g., the portion that extends horizontally in FIG. 3) arranged on a top surface of the second conductive layer **314**, a second area **15b** (e.g., the portion that extends vertically in FIG. 3) arranged to cover the end of the second conductive layer **314** by changing a direction from the first area **15a**, and a third area **15c** (e.g., the portion that extends horizontally alongside the lower substrate **10** in FIG. 3) arranged between an end of the second area **316b** of the first conductive layer **316** and the lower substrate **10** by changing a direction from the second area **15b**.

That is, the second insulating layer **15** is arranged between the first and second conductive layers **316** and **314**, and thus the first conductive layer **316** may be insulated from the second insulated layer **314**. Also, the third area **15c** of the second insulating layer **15** may be arranged between the first conductive layer **316** and the lower substrate **10** in order to prevent problems that occur when adhesion becomes weak due to a direct connection of the first conductive layer **316** (which includes metals, and etc.) to the lower substrate **10**.

A third insulating layer **17** may be a portion that extends from the interlayer insulating layer **17** in the display area DA, and may include a first area **17a** (e.g., the portion that extends horizontally in FIG. 3) arranged on the top surface of the first conductive layer **316**, and a second area **17b** (e.g., the portion that extends vertically in FIG. 3) extended along the side portion of the first conductive layer **316** in the inward direction of the openings **C1** by changing a direction from the first area **17a**.

The third insulating layer **17** may be arranged to cover the first conductive layer **316**, such that the first conductive layer **316** does not directly contact the sealing member **400**.

The lower and upper substrates **10** and **30** are attached by the sealing member **400**, and the sealing member **400** may be formed by spreading a material for forming the sealing member **400** (e.g., frit) and irradiating a laser beam such as a heat source to the material to harden the material.

In this regard, the sealing member **400** may be firmly and evenly hardened throughout the sealing area SA such that the lower and upper substrates **10** and **30** are not easily separated.

Since the insulating layer IL included in the sealing area SA of the organic light-emitting display apparatus includes the openings **C1**, an area of the sealing member **400** that

contacts the third insulating layer **17** and the lower substrate **10** may be increased, thereby improving the adhesion. The sealing member **400** (which includes frit, and etc.) directly contacts the lower substrate **10** (which is, for example, formed of glass or the like), thus further improving the adhesion.

According to the present embodiment, the first and second conductive layers **316** and **314** arranged on the sealing area SA included in the organic light-emitting display apparatus absorb the laser beam for hardening the sealing member **400**, and transfer heat generated by the laser beam to other areas so that the sealing member **400** may be evenly hardened throughout the sealing area SA.

Since the first conductive layer **316** is arranged to cover not only the top surface of the insulating layer IL but also the side portion thereof, absorption and conduction of the laser beam are increased and the sealing member **400** is efficiently hardened. Therefore, the adhesion of the lower and upper substrates **10** and **30** may be increased.

A partition **320** that is formed in the same layer and of the same material as the first insulating layers **11** and **13**, the second insulating layer **15**, and the third insulating layer **17** may be arranged inside the openings included in the insulating layer IL.

By increasing the area where the sealing member **400** contacts the first insulating layers **11** and **13**, the second insulating layer **15**, and the third insulating layer **17** through the partition **320**, the adhesion may be increased.

Referring to FIG. 2, the partition **320** may be arranged in the openings **C1** in a cross shape. However, the present embodiment is not limited thereto. The partition **320** may not be arranged, or may be arranged in different shapes.

FIG. 4 is a schematic cross-sectional view of an organic light-emitting display apparatus according to another embodiment of the present invention.

Referring to FIG. 4, the organic light-emitting display apparatus includes the lower substrate **10** including the sealing area SA included in the display area DA and the non-display area PA of FIG. 1, and the upper substrate **30** placed over the lower substrate **10**. In the sealing area SA, the sealing member **400** attaching the lower and upper substrate **10** and **30** is arranged.

The display area DA may include the sTFT, dTFT, and the OLED that is electrically connected to the dTFT.

Although not illustrated in the drawing, the display area DA may further include other TFTs performing different functions other than the sTFT, and dTFT.

The buffer layer **11** is arranged on the lower substrate **10**, and on the buffer layer **11**, the driving activation layer **212** of the dTFT, and the switching activation layer **112** of the sTFT are arranged. The activation layers **112** and **212** may contain various materials. For example, the activation layers **112** and **212** may contain the inorganic semiconductor materials such as amorphous silicon or crystalline silicon, and may include the source areas **112a** and **212a**, the drain areas **112b** and **212b** doped with the ion impurities, and the channel areas **112c** and **212c** connecting the source areas **112a** and **212a**, and the drain areas **112b** and **212b**. As another example, the activation layers **112** and **212** may include the oxide semiconductors, or the organic semiconductor materials.

On the buffer layer **11**, the first gate insulating layer **13** formed of silicon oxide and/or silicon nitride may be arranged, and the switching gate electrode **114** may be arranged on the first gate insulating layer **13** over the switching activation layer **112**.

On the first gate insulating layer **13**, the second gate insulating layer **15** may be arranged to cover the switching gate

electrode **114**, and on the second gate insulating layer **15**, a driving gate electrode **216** may be arranged.

The switching and driving gate electrodes **114** and **216** may be formed as a single layer or multiple layers including at least one selected from the group consisting of Al, Pt, Pd, Ag, Mg, Au, Ni, Nd, Ir, Cr, Li, Ca, Mo, Ti, W, and Cu.

In the organic light-emitting display apparatus, the gate electrodes of different TFTs are arranged on different layers (or at different levels) such that a distance between gate wiring, which is arranged on different layers, may be shortened, and thus the high resolution may be accomplished.

On the second gate insulating layer **15**, the intermediate insulating layer **17** formed as a single layer or multiple layers including silicon oxide or silicon nitride may be arranged, and on the intermediate insulating layer **17**, the switching source electrode **118a**, the switching drain electrode **118b**, and the driving source electrode **218a** and the driving drain electrode **218b** may be arranged.

Also, on the intermediate insulating layer **17**, the planarization layer **19** may be arranged in order to cover the source electrodes **118a** and **218a**, and the drain electrodes **118b** and **218b**.

On the planarization layer **19**, the OLED including the pixel electrode **121** that is electrically connected to the driving drain electrode **218b**, and the opposite electrode **123** placed over the pixel electrode **121**, and the intermediate layer **122** interposed between the pixel and opposite electrodes **121** and **123** and including the organic emission layer may be arranged.

The pixel defining layer **20** may be arranged on the planarization layer **19**. The pixel defining layer **20** includes the openings exposing the center of the pixel electrode **121**, and defines the pixels. The pixel defining layer **20** may be formed of the organic materials such as polyimide.

The upper substrate **30** placed over the lower substrate **10** may be formed of various materials such as glass, metals, or plastic. The lower and upper substrates **10** and **30** may be attached using the sealing member **400**. The sealing member **400** may include frit, epoxy, or the like, but the present embodiment is not limited thereto and the sealing member **400** may include one or more other materials.

On the lower substrate **10** in the sealing area SA, the insulating layer IL including the openings C1, and the first conductive layer **316** including the first area **316a** (e.g., the portion that extends horizontally in FIG. 4) arranged on the top surface of the insulating layer IL, the second area **316b** (e.g., the portion that extends vertically in FIG. 4) extended along the side portion of the insulating layer IL in the inward direction of the openings C1 of may be arranged.

The insulating layer IL may include the first insulating layers **11** and **13**, the second insulating layer **15**, and the second conductive layer **314** may be arranged therebetween (e.g., between the first insulating layer **13** and the second insulating layer **15**, as shown in FIG. 4).

In the present embodiment, the first and second conductive layers **316** and **314** may be arranged in the same layers (or at the same level) as the driving gate electrode **216** of the dTFT, and the switching gate electrode **114**, and may include the same materials (or include the substantially similar layered structure), respectively.

The first insulating layers **11** and **13** in the sealing area SA may be portions that extends from the buffer layer **11** and the first gate insulating layer **13** in the display area DA, and the second insulating layer **15** in the sealing area SA may be a portion that extends from the second gate insulating layer **15** in the display area DA.

The second insulating layer **15** may include: the first area **15a** (e.g., the portion that extends horizontally in FIG. 4) arranged on the top surface of the second conductive layer **314**; the second area **15b** (e.g., the portion that extends vertically in FIG. 4) arranged to cover the end of the second conductive layer **314** by changing the direction from the first area **15a**; and the third area **15c** (e.g., the portion that extends horizontally alongside the lower substrate **10** in FIG. 4) arranged between the lower substrate **10** and the end of the second area **316b** of the first conductive layer **316** by changing the direction from the second area **15b**.

That is, the second insulating layer **15** is arranged between the first and second conductive layers **316** and **314**, and thus the first conductive layer **316** may be insulated from the second conductive layer **314**. Also, the third area **15c** of the second insulating layer **15** may be arranged between the first conductive layer **316** and the lower substrate **10** in order to prevent the problems with regard to the lower adhesion that is caused by a direct contact between the first conductive layer **316** (which includes metals) and the lower substrate **10**.

The third insulating layer **17** may be arranged on the first conductive layer **316**, and may include the first area **17a** (e.g., the portion that extends horizontally in FIG. 4) arranged on the top surface of the first conductive layer **316**, and the second area **17b** (e.g., the portion that extends vertically in FIG. 4) extended along the side portion of the first conductive layer **316** in the inward direction of the openings C1 by changing the direction from the first area **17a**.

The third insulating layer **17** in the sealing area SA may be a portion that extends from the intermediate layer **17** of the display area DA, and may be arranged to cover the first conductive layer **316** such that the sealing member **400** and the first conductive layer **316** do not contact each other.

In FIG. 4, the sTFT, and dTFT are illustrated for convenience of explanation, but the present embodiment is not limited thereto. In other words, the sTFT and dTFT may be randomly selected first and second TFTs performing different functions, and the switching activation layer, the switching gate electrode, the switching source electrode, and the switching drain electrode may respectively indicate the first activation layer, the first gate electrode, the first source electrode, and the first drain electrode of the first TFT. Also, the driving activation layer, the driving gate electrode, the driving source electrode, and the driving drain electrode may respectively indicate the second activation layer, the second gate electrode, the second source electrode, and the second drain electrode.

FIG. 5 is a cross-sectional view illustrating the sealing area SA included in an organic light-emitting display apparatus, according to another embodiment of the present invention.

Referring to FIG. 5, on the lower substrate **10** in the sealing area SA included in the organic light-emitting display apparatus, the insulating layer IL including the openings C1, and the first conductive layer **316** including the first area **316a** (e.g., the portion that extends horizontally in FIG. 5) arranged on the top surface of the insulating layer IL, and the second area **316b** (e.g., the portion that extends vertically in FIG. 5) extended along the side portion of the insulating layer IL in the inward direction of the openings C1 are arranged.

The insulating layer IL may include the plurality of insulating layers **11**, **13** and **15**, and the partition **320** of FIG. 3 may not be arranged inside the openings C1 included in the insulating layer IL.

Other configurations are the same as the organic light-emitting display apparatus of FIG. 3, and thus no description will be provided.

FIG. 6 is a cross-sectional view illustrating a sealing area SA included in the organic light-emitting display apparatus according to another embodiment of the present invention.

Referring to FIG. 6, on the lower substrate 10 in the sealing area SA included in the organic light-emitting display apparatus, the insulating layer IL including the openings C1, and the first conductive layer 316 including the first area 316a (e.g., the portion that extends horizontally in FIG. 6) arranged on the top surface of the insulating layer IL, and the second area 316b (e.g., the portion that extends vertically in FIG. 6) extended along the side portion of the insulating layer IL in the inward direction of the openings C1 are arranged.

The insulating layer IL may include the plurality of insulating layers 11, 13 and 15, and the partition 320 of FIG. 3 may not be arranged inside the openings C1 included in the insulating layer IL.

The third insulating layer 17 may be arranged on the first conductive layer 316, and may include the first area 17a (e.g., the portion that extends horizontally in FIG. 6) arranged on the top surface of the first conductive layer 316, and the second area 17b (e.g., the portion that extends vertically in FIG. 6) extended along the side portion of the first conductive layer 316 in the inward direction of the openings C1 by changing the direction from the first area 17a.

Other configurations are the same as the organic light-emitting display apparatus of FIG. 3, and thus no description will be provided.

FIG. 7 is a cross-sectional view of a sealing area SA included in the organic light-emitting display apparatus according to another embodiment of the present invention.

Referring to FIG. 7, on the lower substrate 10 in the sealing area SA included in the organic light-emitting display apparatus, the insulating layer IL including the openings C1, and the first conductive layer 316 including the first area 316a (e.g., the portion that extends horizontally in FIG. 7) arranged on the top surface of the insulating layer IL, and the second area 316b (e.g., the portion that extends vertically in FIG. 7) extended along the side portion of the insulating layer IL in the inward direction of the openings C1 are arranged.

The insulating layer IL may include the first insulating layers 11 and 13 and the second insulating layer 15, and the second conductive layer 314 may be arranged therebetween.

The third insulating layer 17 may be arranged on the first conductive layer 316, and may include the first area 17a (e.g., the portion that extends horizontally in FIG. 7) arranged on the top surface of the first conductive layer 316, and the second area 17b (e.g., the portion that extends vertically in FIG. 7) extended along the side portion of the first conductive layer 316 in the inward direction of the openings C1 by changing the direction from the first area 17a.

The second insulating layer 15 may include the first area 15a (e.g., the portion that extends horizontally in FIG. 7) arranged on the top surface of the second conductive layer 314, and the second area 15b (e.g., the portion that extends vertically in FIG. 7) covering the end of the second conductive layer 314, and the first and second conductive layers 316 and 314 may be insulated by the second insulating layer 15.

The second conductive layer 314 according to the present embodiment may be arranged in an area that is inward from the ends of the first insulating layers 11, 13 at a predetermined distance, and the first insulating layers 11 and 13 and the second insulating layer 15 may include the same etched surface.

That is, the top surface and the end of the second conductive layer 314 may be completely covered with the second insulating layer 15. Therefore, the second conductive layer

314 may be separated from the first conductive layer 316 that is arranged on the second insulating layer 15, by the second insulating layer 15.

Other configurations are the same as the organic light-emitting display apparatus of FIG. 3, and thus no description will be provided.

FIG. 8 is a cross-sectional view of a sealing area SA included in the organic light-emitting display apparatus according to another embodiment of the present invention.

Referring to FIG. 8, on the lower substrate 10 in the sealing area SA included in the organic light-emitting display apparatus, the insulating layer IL including the openings C1, and the first conductive layer 316 including the first area 316a (e.g., the portion that extends horizontally in FIG. 8) arranged on the top surface of the insulating layer IL, and the second area 316b (e.g., the portion that extends vertically in FIG. 8) extended along the side portion of the insulating layer IL in the inward direction of the openings C1 are arranged.

The insulating layer IL may include the first insulating layer 13 and second insulating layer 15, and the second conductive layer 314 may be arranged therebetween.

The third insulating layer 17 may be arranged on the first conductive layer 316, and may include the first area 17a (e.g., the portion that extends horizontally in FIG. 8) arranged on the top surface of the first conductive layer 316, and the second area 17b (e.g., the portion that extends vertically in FIG. 8) extended along the side portion of the first conductive layer 316 in the inward direction of the openings C1 by changing the direction from the first area 17a.

The second insulating layer 15 may include the first area 15a (e.g., the portion that extends horizontally in FIG. 8) arranged on the top surface of the second conductive layer 314, and the second area 15b (e.g., the portion that extends vertically in FIG. 8) covering the end of the second conductive layer 314, and the first and second conductive layers 316 and 314 may be insulated by the second insulating layer 15.

The second conductive layer 314 according to the present embodiment may be arranged in an area that is inward from the ends of the first insulating layer 11 at a predetermined distance, and the first insulating layer 13 and the second insulating layer 15 may have the same etched surface.

That is, the top surface and the end of the second conductive layer 314 may be completely covered with the second insulating layer 15. Therefore, the second conductive layer 314 may be separated from the first conductive layer 316 that is arranged on the second insulating layer 15, by the second insulating layer 15.

In the present embodiment, the first insulating layer 13 is formed as a single layer, and the buffer layer 11 may be arranged at the bottom of the first insulating layer 13. The buffer layer 11 may not include the openings C1, and may be arranged throughout the lower substrate 10. Accordingly, the sealing member 400 and the lower substrate 10 may not directly contact each other.

Other configurations are the same as the organic light-emitting display apparatus of FIG. 3, and thus no description will be provided.

FIG. 9 is a cross-sectional view, taken along a line IX-IX' of FIG. 2, according to an embodiment of the present invention.

Referring to FIGS. 2 and 9, in the sealing area SA included in the organic light-emitting display apparatus, the sealing member 400 attaching the lower and upper substrates 10 and 30 is arranged, and on the lower substrate 10 in the sealing area SA, the insulating layer IL including the openings C1 is arranged.

The sealing member 400 may be formed after spreading a material for forming the sealing member 400 such as frit, and

irradiating the laser beam as a heat source to the material for hardening. In general, intensity of the laser beam is high at the center, but decreases as the laser beam moves farther away from the center, which is referred to the Gaussian distribution.

Accordingly, when irradiating the sealing member **400** with the laser beam, the intensity of the laser beam at the center Ct of the sealing member **400** (or sealing area SA) is high, but that of the laser beam at the edge Eg of the sealing member **400** (or sealing area SA) may be low.

Due to this difference, the sealing member **400** may not be evenly hardened throughout the entire area.

In the organic light-emitting display apparatus according to the present embodiment, the first conductive layer **316** is arranged on an edge Eg of the sealing member **400** as described above so that the absorption and conduction of the light irradiated to the edge Eg may be improved.

Referring to FIG. 9, on the lower substrate **10** at the edge Eg of the sealing area SA, the insulating layer IL including the openings C1, and the first conductive layer **316** including the first area **316a** (e.g., the portion that extends horizontally in FIG. 9) arranged on the top surface of the insulating layer IL, and the second area **316b** (e.g., the portion that extends vertically in FIG. 9) extended along the side portion of the insulating layer IL in the inward direction of the openings C1 are arranged.

The insulating layer IL may include the first insulating layers **11** and **13** and the second insulating layers **15**, and the second conductive layer **314** may be arranged therebetween.

The second insulating layer **15** may include: a first area **15a** (e.g., the portion that extends horizontally in FIG. 9) arranged on the top surface of the second conductive layer **314**; a second area **15b** (e.g., the portion that extends vertically in FIG. 9) arranged to cover the end of the second conductive layer **314** by changing the direction from the first area **15a**; and the third area **15c** (e.g., the portion that extends horizontally alongside the lower electrode **10** in FIG. 9) arranged between the end of the second area **316b** of the first conductive layer **316** and the lower substrate **10** by changing the direction from the second area **15b**.

The third insulating layer **17** may be arranged on the first conductive layer **316**, and may include the first area **17a** (e.g., the portion that extends horizontally in FIG. 9) arranged on the top surface of the first conductive layer **316**, and the second area **17b** (e.g., the portion that extends vertically in FIG. 9) extended along the side portion of the first conductive layer **316** in the inward direction of the openings C1 by changing the direction from the first area **17a**.

The partition **320** that is formed on the same layer (or at the same level) and of the same material (or of the same layered structure) as the first insulating layers **11** and **13**, the second insulating layer **15**, and the third insulating layer **17** may be arranged inside the openings C1 included in the insulating layer IL.

On the lower substrate **10** in the center Ct of the sealing member **400**, the insulating layer IL including the openings C1, the first insulating layers **11** and **13**, and the second insulating layer **15**, and the third insulating layer **17** arranged on the second insulating layer **15** may be arranged.

The second conductive layer **314** may be arranged between the first insulating layers **11** and **13** and the second insulating layer **15**, and the partition **320** that is formed on the same layer and of the same material as the first insulating layers **11** and **13**, the second insulating layer **15**, and the third insulating layer **17** may be arranged inside the openings C1 included in the insulating layer IL.

That is, the first conductive layer **316** covering the top surface and the side portion of the insulating layer IL may not

be arranged at the center Ct of the sealing member **400**. The second conductive layer **314** may absorb the laser beam, and conduct the heat generated due to the absorption of the laser beam. However, the second conductive layer **314** is not extended into the insides of the openings C1 so that the first and second conductive layers **316** and **314** may have different absorption of the laser beam and heat conduction.

Therefore, uneven intensity of the laser beam irradiated to the sealing member **400** may be eliminated due to the above configuration, and thus the entire area of the sealing member **300** may be evenly hardened.

As described above, according to the one or more of the above embodiments of the present invention, the organic light-emitting display apparatus hardens the sealing member evenly and efficiently, and thus adhesion of the lower and upper substrates may be improved.

It should be understood that the exemplary embodiments described therein should be considered in a descriptive sense only and not for purposes of limitation. Descriptions of features or aspects within each embodiment should typically be considered as available for other similar features or aspects in other embodiments.

While one or more embodiments of the present invention have been described with reference to the figures, it will be understood by those of ordinary skill in the art that various changes in form and details may be made therein without departing from the spirit and scope of the present invention as defined by the following claims.

What is claimed is:

1. An organic light-emitting display apparatus comprising:
 - a lower substrate comprising a major surface which comprises a display area for displaying an image thereon and a sealing area surrounding the display area when viewed in a direction perpendicular to the major surface;
 - an insulating structure disposed over the lower substrate in both the display area and the sealing area;
 - a plurality of openings formed through the insulating structure in the sealing area, the plurality of openings comprising inner side surfaces;
 - a first conductive layer disposed in the sealing area, comprising:
 - a first portion over the insulating structure extending in a horizontal direction that is generally parallel to the major surface, and
 - a second portion extending on at least part of the inner side surfaces of the plurality of openings in a vertical direction that is generally perpendicular to the major surface;
 - a second conductive layer disposed directly under the first conductive layer in the sealing area;
 - an upper substrate placed over the lower substrate; and
 - a sealing member interposed between the lower substrate and the upper substrate in the sealing area thereof and filling the plurality of openings, wherein the sealing member is in contact with the lower substrate through the plurality of openings, thereby integrating the lower and upper substrates, and
 - wherein the first and second conductive layers are insulated from the lower substrate and the sealing member, and the first conductive layer is insulated from the second conductive layer.

2. The organic light-emitting display apparatus of claim 1, wherein the insulating structure comprises a plurality of insulating layers.

3. The organic light-emitting display apparatus of claim 2, wherein the plurality of insulating layers comprise a first insulating layer and a second insulating layer over the first insulating layer,

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wherein the second conductive layer interposed between the first and second insulating layers of the insulating structure.

4. The organic light-emitting display apparatus of claim 3, wherein the second insulating layer comprises:

a first portion formed over the second conductive layer and extending generally in the horizontal direction; and
a second portion formed on a side surface of the second conductive layer and extending generally in the vertical direction, thereby providing at least part of the inner side surfaces of one of the plurality of openings.

5. The organic light-emitting display apparatus of claim 4, wherein the second insulating layer further comprises a third portion extending from second portion generally in the horizontal direction.

6. The organic light-emitting display apparatus of claim 1, further comprising a third insulating layer disposed on the first conductive layer.

7. The organic light-emitting display apparatus of claim 6, wherein the third insulating layer further comprises:

a first portion extending generally in the horizontal direction on the first portion of the first conductive layer; and
a second portion formed on the second portion of the first conductive layer and extending generally in the vertical direction.

8. The organic light-emitting display apparatus of claim 1, further comprising a partition disposed inside the sealing area.

9. The organic light-emitting display apparatus of claim 8, wherein the partition comprises generally a same layered structure as the insulating structure.

10. The organic light-emitting display apparatus of claim 3, further comprising:

a first thin film transistor (TFT) comprising a first activation layer and a first gate electrode disposed in the display area; and a second TFT comprising a second activation layer and a second gate electrode disposed in the display area,
wherein the first and second gate electrodes are at different levels.

11. The organic light-emitting display apparatus of claim 10, wherein the first conductive layer is arranged at the same level as the second gate electrode, and the second conductive layer is arranged at the same level as the first gate electrode.

12. The organic light-emitting display apparatus of claim 11, further comprising:

a first gate insulating layer interposed between the first activation layer and the first gate electrode; and
a second gate insulating layer disposed on the first gate electrode,

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wherein the second activation layer is disposed at the same level as the first activation layer, and

the second gate electrode is disposed on the second gate insulating layer over the second activation layer.

13. The organic light-emitting display apparatus of claim 12, wherein the first insulating layer in the sealing area comprises a portion that extends from the first gate insulating layer in the display area, and the second insulating layer in the sealing area comprises a portion that extends from the second gate insulating layer in the display area.

14. The organic light-emitting display apparatus of claim 3, further comprising:

a driving thin film transistor comprising a driving activation layer and a driving gate electrode;

a capacitor comprising the driving gate electrode functioning as a lower electrode, and an upper electrode;

a first gate insulating layer interposed between the driving activation layer and the driving gate electrode; and

a second gate insulating layer interposed between the driving gate electrode and the upper electrode.

15. The organic light-emitting display apparatus of claim 14, wherein the first conductive layer is disposed at the same level as the upper electrode, and the second conductive layer is disposed at the same level as the driving gate electrode.

16. The organic light-emitting display apparatus of claim 14, wherein the first insulating layer in the sealing area comprises a portion that extends from the first gate insulating layer in the display area, and the second insulating layer in the sealing area comprises a portion that extends from the second gate insulating layer in the display area.

17. The organic light-emitting display apparatus of claim 1, wherein the first conductive layer is disposed only at an edge of the sealing area.

18. The organic light-emitting display apparatus of claim 1, wherein the insulating structure, the first conductive layer, and the second conductive layer are disposed at an edge of the sealing area.

19. The organic light-emitting display apparatus of claim 1, further comprising at least one organic light-emitting device disposed in the display area,

wherein the at least one organic light-emitting device comprises:

a pixel electrode;

an opposite electrode placed over the pixel electrode; and

an intermediate layer arranged between the pixel electrode and the opposite electrode, and comprising an organic emission layer.

20. The organic light-emitting display apparatus of claim 1, wherein the sealing member comprises frit.

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专利名称(译)	有机发光显示装置		
公开(公告)号	US9147718	公开(公告)日	2015-09-29
申请号	US14/273311	申请日	2014-05-08
[标]申请(专利权)人(译)	三星显示有限公司		
申请(专利权)人(译)	三星DISPLAY CO. , LTD.		
当前申请(专利权)人(译)	三星DISPLAY CO. , LTD.		
[标]发明人	KIM DO HOON		
发明人	KIM, DO-HOON		
IPC分类号	H01L27/32		
CPC分类号	H01L27/3258 H01L27/3276 H01L27/3244 H01L51/5246 H01L51/5203 H01L51/5237 H01L2251/53 H05B33/04		
审查员(译)	艾哈迈德, KHAJA		
优先权	1020130126114 2013-10-22 KR		
其他公开文献	US20150108438A1		
外部链接	Espacenet USPTO		

摘要(译)

一种有机发光显示装置，包括：下基板，包括主表面，当在垂直于主表面的方向上观察时，所述下基板包括显示区域和围绕显示区域的密封区域；绝缘结构，设置在显示区域和密封区域中的下基板上；在密封区域中穿过绝缘结构形成的多个开口，开口包括内侧表面；第一导电层，包括在水平方向上延伸的绝缘结构上方的第一部分；以及第二部分，在垂直方向上在开口的内侧表面的至少一部分上延伸；上基板放置在下基板上；密封构件介于下基板和上基板之间的密封区域中并且填充开口，从而使下基板和上基板一体化。

